

APPENDIX D – MODIFICATION LIST

1. On the Mainframe Assembly.

Before	After
	
1) Backside of mainframe is split to two pieces.	

2. On the backside of mainframe and bracket.

Before	After
	
1) Add the bracket for attaching the backside of mainframe	

3. On the bracket for attaching the backside of mainframe

Before	After
<p>There is no bracket before 2 piece of mainframe model.</p>	

1) Add the EMI gasket for increasing conductance between mainframes and bracket.

4. EMI Gasket on top of LCD panel

Before	After
	

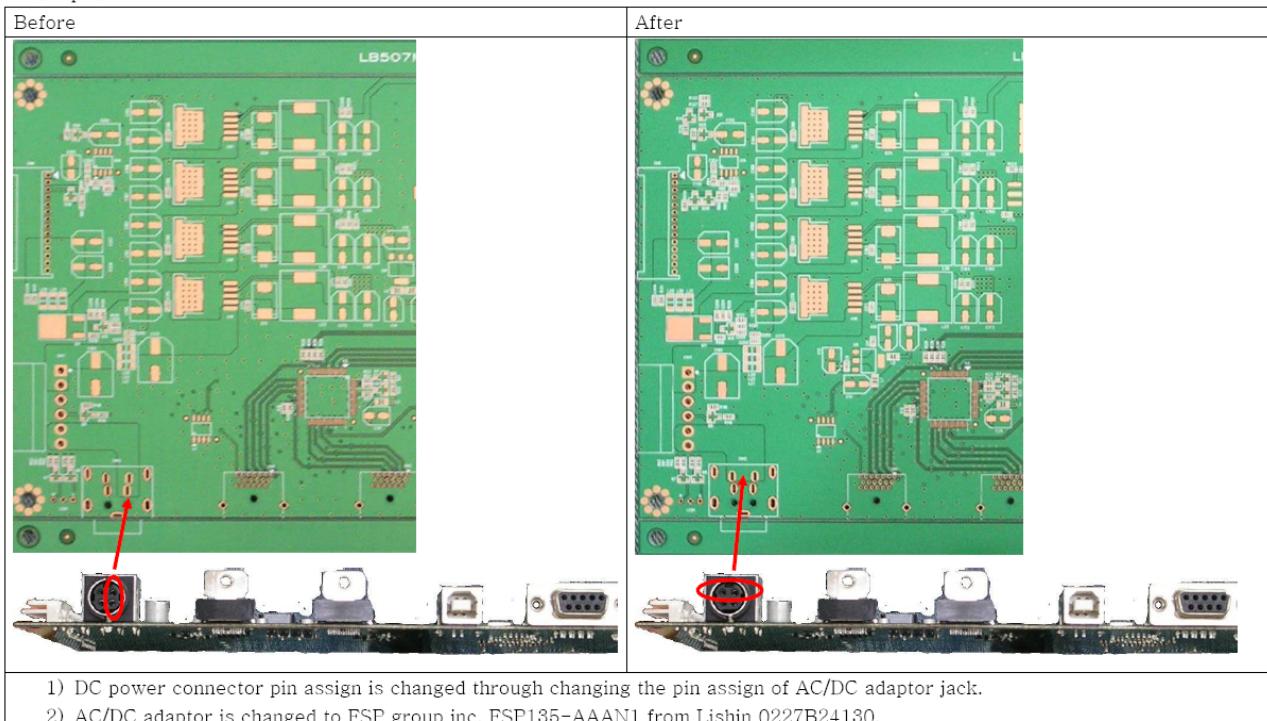
1) Cut off the EMI Gasket on top of LCD panel for attaching Thermal pad.

5. On the side-plate



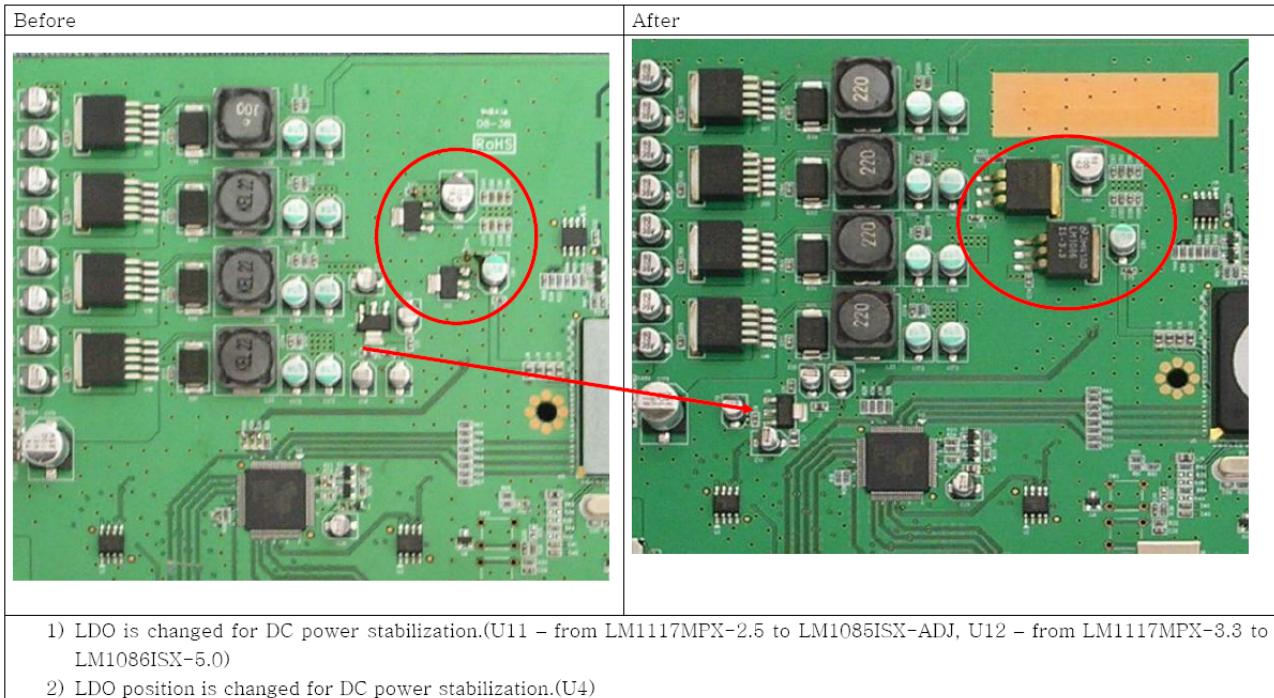
1) Glue point of double stick EMI Tape is changed since the assembly method of the side-plate is changed.

6. DC power connector



1) DC power connector pin assign is changed through changing the pin assign of AC/DC adaptor jack.
 2) AC/DC adaptor is changed to FSP group inc. FSP135-AAAN1 from Lishin 0227B24130.

7. Power source



APPENDIX E – BLOCK DIAGRAM

APPENDIX F – USER'S MANUAL

APPENDIX G – SCHEMATIC DIAGRAM
